Docket No.:

HI-0274

DECLARATION AND POWER OF ATTORNEY

As a below named invento	or, I hereby de clare that:	
My residence, post office	and citizenship are as stated below next to	о ту пате,
are listed below) of the sul	first and sole inventor (if only one name bject matter claimed and for which a pate the specification of which	is listed below) or an original, first and joint inventor (if plural names nt is sought on the invention entitled <u>AIR FLOW PASSAGE OF</u>
is attached hereto	was filed on 4/14/2006 was amended on (if applica	as Application Serial No. 10/575,856 and ble)
including the claims, as an	I hereby state that I have reviewed and nended by any amendment referred to abo	and erstand the contents of the above identified specification, ove.
accordance with Title 37, 0	I acknowledge the duty to disclose info Code of Federal Regulations, Section 1.56	trnation which is known to me to be material to patentability in (a).
States of America, listed be	cate, or 365(a) of any PCT international a clow and have also identified below, by cl	under 35 U.S.C. 119(a)-(d) or 365 (b) of any foreign application(s) for pplication which designated at least one country other than the United necking the box, any foreign application for patent or inventor's the before that of the application on which priority is claimed.
Prior Foreign Applicatio <u>Number</u>	n(s): <u>Country</u>	Foreign Filing Date Month/Day/Year
72118/2003	KOREA	OCTOBER 16, 2003
I hereby claim the benefit	under 35 U.S.C. 119(e) of any United Stat	tes provisional application(s) listed below.
Application Number(s):	·	Filing Date (Month/Day/Year)
designating the United Sta disclosed in the prior Unit acknowledge the duty to	tes of America, listed below and, insofar ted States or PCT international application disclose information which is material	States application(s), or 365(c) of any PCT international application as the subject matter of each of the claims of this application is not on in the manner provided by the first paragraph of 35 U.S.C. 112, I to patentability as defined in 37 CFR 1.56 which became available PCT international filing date of this application.
Prior U. S. Application or PCT Parent Number	Filing Date (Month	/Day/Year) Parent Patent Number (if applicable)
PCT/KR2004/002631	OCTOBER 15, 2004	
[b b		

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

I hereby appoint the attorney(s) and/or agent(s) associated with Customer Number 34610 to prosecute this application and transact all business in the Patent and Trademark Office.

Direct all correspondence to Customer Number 34610

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Inventor's signature: Date:
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- · · ·
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Full name of joint inventor(s): Inventor's signature: Date:
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Full name of joint inventor(s): Inventor's signature: Mailing Address: Citizenship: Residence:
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